

256K x 16 Static RAM

Features

- · High speed
 - $-t_{AA} = 15 \text{ ns}$
- Low active power
 - -612 mW (max.)
- Low CMOS standby power (Commercial L version)
 - -1.8 mW (max.)
- 2.0V Data Retention (600 μW at 2.0V retention)
- Automatic power-down when deselected
- TTL-compatible inputs and outputs
- Easy memory expansion with $\overline{\text{CE}}$ and $\overline{\text{OE}}$ features

Functional Description

The CY7C1041V33 is a high-performance CMOS Static RAM organized as 262,144 words by 16 bits.

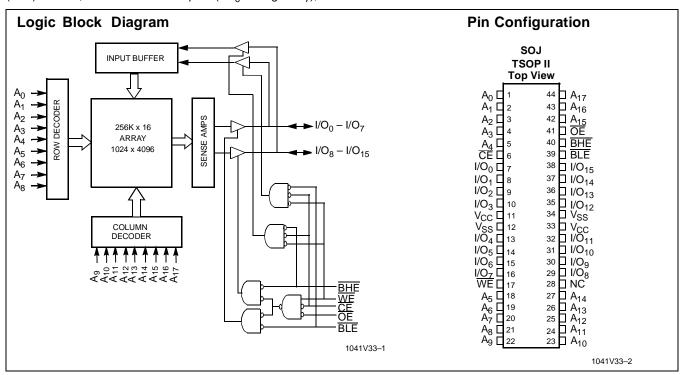
Writing to the device is accomplished by taking Chip Enable (\overline{CE}) and Write Enable (\overline{WE}) inputs LOW. If Byte Low Enable (\overline{BLE}) is LOW, then data from I/O pins $(I/O_0$ through I/O₇), is

written into the location specified on the address pins (A_0 through A_{17}). If Byte High Enable (\overline{BHE}) is LOW, then data from I/O pins (I/O $_8$ through I/O $_{15}$) is written into the location specified on the address pins (A_0 through A_{17}).

Reading from the device is accomplished by taking Chip Enable ($\overline{\text{CE}}$) and Output Enable ($\overline{\text{OE}}$) LOW while forcing the Write Enable ($\overline{\text{WE}}$) HIGH. If Byte Low Enable ($\overline{\text{BLE}}$) is LOW, then data from the memory location specified by the address pins will appear on I/O $_0$ to I/O $_7$. If Byte High Enable ($\overline{\text{BHE}}$) is LOW, then data from memory will appear on I/O $_8$ to I/O $_{15}$. See the truth table at the back of this data sheet for a complete description of read and write modes.

The input/output pins (I/O $_0$ through I/O $_{15}$) are placed in a high-impedance state when the device is deselected ($\overline{\text{CE}}$ HIGH), the outputs are disabled ($\overline{\text{OE}}$ HIGH), the $\overline{\text{BHE}}$ and $\overline{\text{BLE}}$ are disabled ($\overline{\text{BHE}}$, $\overline{\text{BLE}}$ HIGH), or during a write operation ($\overline{\text{CE}}$ LOW, and $\overline{\text{WE}}$ LOW).

The CY7C1041V33 is available in a standard 44-pin 400-mil-wide body width SOJ and 44-pin TSOP II package with center power and ground (revolutionary) pinout.



Selection Guide

	1041V33-12	1041V33-15	1041V33-17	1041V33-20	1041V33-25		
Maximum Access Time (ns)	12	15	17	20	25		
Maximum Operating Current (mA)			190	170	160	150	130
Maximum CMOS Standby Current (mA) Com'l/Ind'l		8	8	8	8	8	
	Com'l	L	0.5	0.5	0.5	0.5	0.5

Shaded areas contain preliminary information.



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature-65°C to +150°C

Ambient Temperature with

Power Applied......–55°C to +125°C

Supply Voltage on V_{CC} to Relative $GND^{[1]}$ -0.5V to +4.6V

DC Voltage Applied to Outputs in High Z State $^{[1]}$-0.5V to V CC + 0.5V

DC Input Voltage ^[1]	0.5V to V _{CC} + 0.5V
Current into Outputs (LOW)	20 mA

Operating Range

Range	Ambient Temperature ^[2]	v _{cc}
Commercial	0°C to +70°C	$3.3V\pm0.3V$
Industrial	–40°C to +85°C	

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditi	ons	7C104	1-12V33	7C104	1V33-15	
				Min.	Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min.,$ $I_{OH} = -4.0 \text{ mA}$		2.4		2.4		V
V _{OL}	Output LOW Voltage	$V_{CC} = Min.,$ $I_{OL} = 8.0 \text{ mA}$			0.4		0.4	V
V _{IH}	Input HIGH Voltage		2.2	V _{CC} + 0.5	2.2	V _{CC} + 0.5	V	
V _{IL}	Input LOW Voltage ^[1]			-0.5	0.8	-0.5	0.8	V
I _{IX}	Input Load Current	$GND \leq V_I \leq V_CC$		-1	+1	-1	+1	μΑ
I _{OZ}	Output Leakage Current	GND ≤ V _{OUT} ≤ V _{CC} , Ou	tput Disabled	-1	+1	-1	+1	μΑ
Icc	V _{CC} Operating Supply Current	$V_{CC} = Max., f = f_{MAX} =$	1/t _{RC}		190		170	mA
I _{SB1}	Automatic CE Power-Down Current —TTL Inputs	Max. V_{CC} , $\overline{CE} \ge V_{IH}$ $V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$, $f = f_{MAX}$			40		40	mA
I _{SB2}	Automatic CE	Max. V _{CC} ,	Com'l/Ind'l		8		8	mA
	Power-Down Current —CMOS Inputs	$\overline{CE} \ge V_{CC} - 0.3V$, $V_{IN} \ge V_{CC} - 0.3V$, or $V_{IN} \le 0.3V$, f=0	Com'l L		0.5		0.5	mA

Shaded areas contain preliminary information.

V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns.
 T_A is the "Instant On" case temperature.



Electrical Characteristics Over the Operating Range (continued)

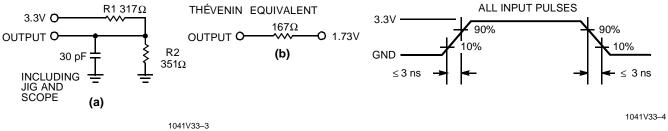
		Test Conditions		1041	V33-17	1041	V33-20	1041V33-25		
Parameter	Description			Min.	Max.	Min.	Max.	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0$	mA	2.4		2.4		2.4		V
V _{OL}	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 8.0 r$	nΑ		0.4		0.4		0.4	V
V _{IH}	Input HIGH Voltage			2.2	V _{CC} + 0.5	2.2	V _{CC} + 0.5	2.2	V _{CC} + 0.5	V
V _{IL}	Input LOW Voltage ^[1]			-0.5	0.8	-0.5	0.8	-0.5	0.8	V
I _{IX}	Input Load Current	$GND \leq V_1 \leq V_{CC}$		-1	+1	-1	+1	-1	+1	μΑ
I _{OZ}	Output Leakage Current	$\begin{array}{l} \text{GND} \leq \text{V}_{\text{OUT}} \leq \text{V}_{\text{CC}}, \\ \text{Output Disabled} \end{array}$		-1	+1	-1	+1	-1	+1	μΑ
Icc	V _{CC} Operating Supply Current	$V_{CC} = Max.,$ $f = f_{MAX} = 1/t_{RC}$			160		150		130	mA
I _{SB1}	Automatic CE Power-Down Current —TTL Inputs	$\begin{aligned} &\text{Max. V}_{\text{CC}}, \overline{\text{CE}} \geq \text{V}_{\text{IH}} \\ &\text{V}_{\text{IN}} \geq \text{V}_{\text{IH}} \text{ or} \\ &\text{V}_{\text{IN}} \leq \text{V}_{\text{IL}}, f = f_{\text{MAX}} \end{aligned}$			40		40		40	mA
I _{SB2}	Automatic CE	Max. V _{CC} ,	Com'l/Ind	'	8		8		8	mA
	Power-Down Current —CMOS Inputs	$\overline{\text{CE}} \ge \text{V}_{\text{CC}} - 0.3\text{V},$ $\text{V}_{\text{IN}} \ge \text{V}_{\text{CC}} - 0.3\text{V},$ or $\text{V}_{\text{IN}} \le 0.3\text{V},$ f=0	Com'l	L	0.5		0.5		0.5	mA

Capacitance^[3]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_A = 25$ °C, f = 1 MHz, $V_{CC} = 3.3$ V	8	pF
C _{OUT}	I/O Capacitance		8	pF

Note:

AC Test Loads and Waveforms



^{3.} Tested initially and after any design or process changes that may affect these parameters.



Switching Characteristics^[4] Over the Operating Range

		1041	V33-12	1041V33-15		1041V33-17		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYCLE	<u> </u>		•	•	•	•		
t _{RC}	Read Cycle Time	12		15		17		ns
t _{AA}	Address to Data Valid		12		15		17	ns
t _{OHA}	Data Hold from Address Change	3		3		3		ns
t _{ACE}	CE LOW to Data Valid		12		15		17	ns
t _{DOE}	OE LOW to Data Valid		6		7		8	ns
t _{LZOE}	OE LOW to Low Z	0		0		0		ns
t _{HZOE}	OE HIGH to High Z ^[5, 6]		6		7		7	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		3		3		ns
t _{HZCE}	CE HIGH to High Z ^[5, 6]		6		7		7	ns
t _{PU}	CE LOW to Power-Up	0		0		0		ns
t _{PD}	CE HIGH to Power-Down		12		15		17	ns
t _{DBE}	Byte Enable to Data Valid		6		7		7	ns
t _{LZBE}	Byte Enable to Low Z	0		0		0		ns
t _{HZBE}	Byte Disable to High Z		6		7		8	ns
WRITE CYCL	E ^[7, 8]		•	•	•	•		
t _{WC}	Write Cycle Time	12		15		17		ns
t _{SCE}	CE LOW to Write End	10		12		12		ns
t _{AW}	Address Set-Up to Write End	10		12		12		ns
t _{HA}	Address Hold from Write End	0		0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		0		ns
t _{PWE}	WE Pulse Width	10		12		12		ns
t _{SD}	Data Set-Up to Write End	7		8		9		ns
t _{HD}	Data Hold from Write End	0		0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		3		3		ns
t _{HZWE}	WE LOW to High Z ^[5, 6]		6		7		8	ns
t _{BW}	Byte Enable to End of Write	10		12		12		ns

Shaded areas contain preliminary information.

Notes:

<sup>Notes:
4. Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified loL/loH and 30-pF load capacitance.
5. that are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage.
6. At any given temperature and voltage condition, that is less than that it less than that less</sup>



$\textbf{Switching Characteristics}^{[4]} \ \text{Over the Operating Range (continued)}$

		1041\	/33-20	1041\		
Parameter	Description	Min.	Max.	Min.	Max.	Unit
READ CYC	LE	<u>.</u>				
t _{RC}	Read Cycle Time	20		25		ns
t _{AA}	Address to Data Valid		20		25	ns
t _{OHA}	Data Hold from Address Change	3		5		ns
t _{ACE}	CE LOW to Data Valid		20		25	ns
t _{DOE}	OE LOW to Data Valid		8		10	ns
t _{LZOE}	OE LOW to Low Z	0		0		ns
t _{HZOE}	OE HIGH to High Z ^[5, 6]		8		10	ns
t _{LZCE}	CE LOW to Low Z ^[6]	3		5		ns
t _{HZCE}	CE HIGH to High Z ^[5, 6]		8		10	ns
t _{PU}	CE LOW to Power-Up	0		0		ns
t _{PD}	CE HIGH to Power-Down		20		25	ns
t _{DBE}	Byte Enable to Data Valid		8		10	ns
t _{LZBE}	Byte Enable to Low Z	0		0		ns
t _{HZBE}	Byte Disable to High Z		8		10	ns
WRITE CYC	LE ^[7,8]	<u>.</u>				
t _{WC}	Write Cycle Time	20		25		ns
t _{SCE}	CE LOW to Write End	13		15		ns
t _{AW}	Address Set-Up to Write End	13		15		ns
t _{HA}	Address Hold from Write End	0		0		ns
t _{SA}	Address Set-Up to Write Start	0		0		ns
t _{PWE}	WE Pulse Width	13		15		ns
t _{SD}	Data Set-Up to Write End	9		10		ns
t _{HD}	Data Hold from Write End	0		0		ns
t _{LZWE}	WE HIGH to Low Z ^[6]	3		5		ns
t _{HZWE}	WE LOW to High Z ^[5, 6]		8		10	ns
t _{BW}	Byte Enable to End of Write	13		15		ns

Data Retention Characteristics Over the Operating Range (For L version only)

Parameter	Parameter Description Conditions ^[10]		Min.	Max.	Unit
V_{DR}	V _{CC} for Data Retention		2.0		V
I _{CCDR}	Data Retention Current	$\frac{V_{CC}}{Q_{CC}} = V_{DR} = 2.0V,$		330	μΑ
t _{CDR} ^[3]	Chip Deselect to Data Retention Time	$\overrightarrow{CE} \ge V_{CC} - 0.3V$, $V_{IN} \ge V_{CC} - 0.3V$ or $V_{IN} \le 0.3V$	0		ns
t _R ^[9]	Operation Recovery Time		t _{RC}		ns

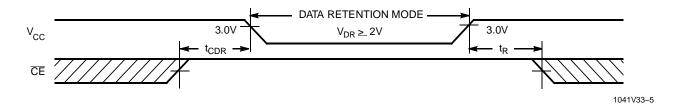
Notes:

^{9.} $t_r \le 3$ ns for the -12 and -15 speeds. $t_r \le 5$ ns for the -20 and slower speeds. 10. No input may exceed V_{CC} + 0.5V.

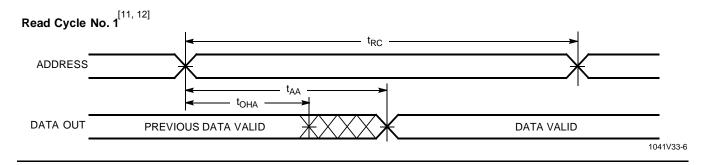
1041V33-7



Data Retention Waveform



Switching Waveforms



Read Cycle No. 2 ($\overline{\text{OE}}$ Controlled) [12, 13] **ADDRESS** t_{RC} CE t_{ACE} ŌΕ t_{HZOE} t_{DOE} BHE, BLE t_{LZOE} → ← t_{HZCE} t_{DBE} t_{LZBE} t_{HZBE} HIGH IMPEDANCE HIGH IMPEDANCE DATA OUT -DATA VALID t_{LZCE} t_{PD} t_{PU} I_{CC} V_{CC} SUPPLY

CURRENT

11. Device is continuously selected. \overline{OE} , \overline{CE} , \overline{BHE} and/or $\overline{BHE} = V_{\parallel}$.

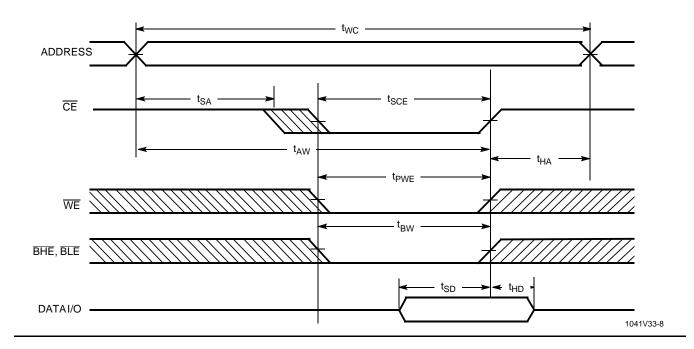
50%

- WE is HIGH for read cycle.
 Address valid prior to or coincident with CE transition LOW.

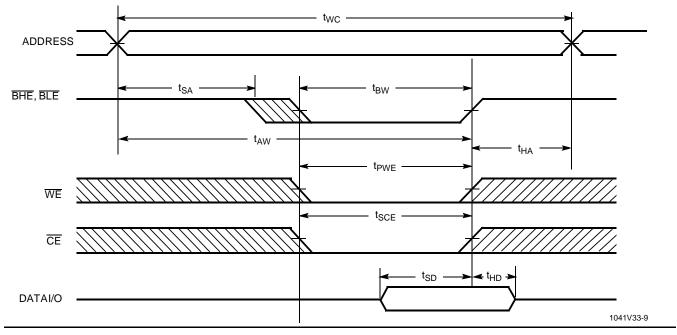


Switching Waveforms (continued)

Write Cycle No. 1 ($\overline{\text{CE}}$ Controlled) $^{[14, 15]}$



Write Cycle No. 2 (BLE or BHE Controlled)



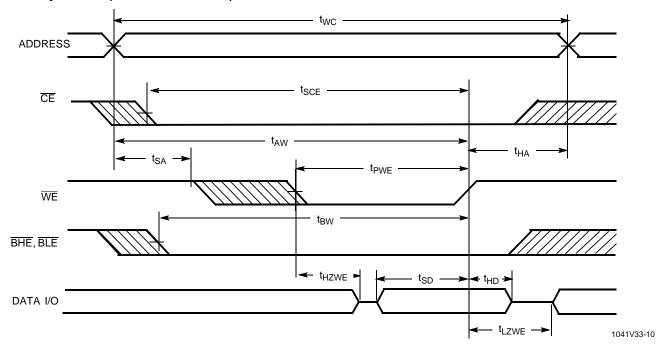
Notes:

- 14. Data I/O is high impedance if OE or BHE and/or BLE= V_{IH}.
 15. If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.



Switching Waveforms (continued)

Write Cycle No.3 (WE Controlled, LOW)



Truth Table

CE	ΘE	WE	BLE	BHE	I/O ₀ –I/O ₇	I/O ₈ -I/O ₁₅	Mode	Power
Н	Х	Χ	Χ	Х	High Z	High Z	Power Down	Standby (I _{SB})
L	L	Н	L	L	Data Out	Data Out	Read All Bits	Active (I _{CC})
L	L	Н	L	Н	Data Out	High Z	Read Lower Bits Only	Active (I _{CC})
L	L	Н	Н	L	High Z	Data Out	Read Upper Bits Only	Active (I _{CC})
L	Х	L	L	L	Data In	Data In	Write All Bits	Active (I _{CC})
L	Χ	L	L	Н	Data In	High Z	Write Lower Bits Only	Active (I _{CC})
L	Х	L	Н	L	High Z	Data In	Write Upper Bits Only	Active (I _{CC})
L	Н	Н	Χ	Х	High Z	High Z	Selected, Outputs Disabled	Active (I _{CC})



Ordering Information

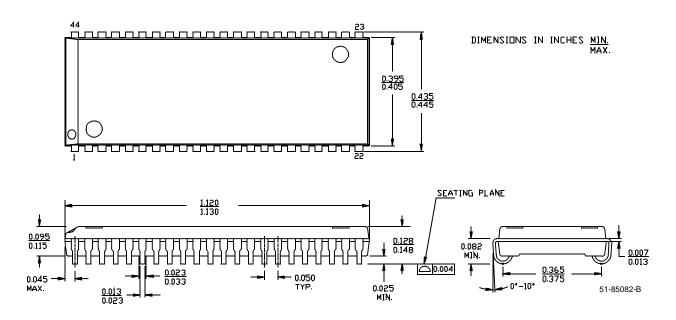
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
12	CY7C1041V33 -12VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1041V33L-12VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33 - 12ZC	Z44	44-Pin TSOP II Z44	
	CY7C1041V33L-12ZC	Z44	44-Pin TSOP II Z44	
15	CY7C1041V33 -15VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33L-15VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33 - 15ZC	Z44	44-Pin TSOP II Z44	
	CY7C1041V33L-15ZC	Z44	44-Pin TSOP II Z44	
17	CY7C1041V33 - 17VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33L-17VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33 - 17ZC	Z44	44-Pin TSOP II Z44	
	CY7C1041V33L-17ZC	Z44	44-Pin TSOP II Z44	
20	CY7C1041V33 - 20VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33L-20VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33 - 20ZC	Z44	44-Pin TSOP II Z44	
	CY7C1041V33L-20ZC	Z44	44-Pin TSOP II Z44	
25	CY7C1041V33 - 25VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33L-25VC	V34	44-Lead (400-Mil) Molded SOJ	
	CY7C1041V33 - 25ZC	Z44	44-Pin TSOP II Z44	
	CY7C1041V33L-25ZC	Z44	44-Pin TSOP II Z44	

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Package Diagrams

44-Lead (400-Mil) Molded SOJ V34

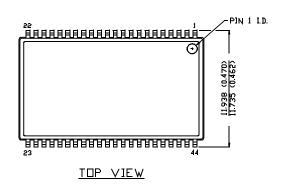


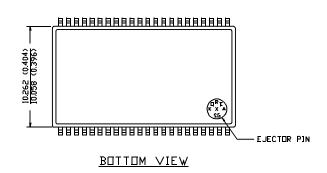
44-Pin TSOP II Z44

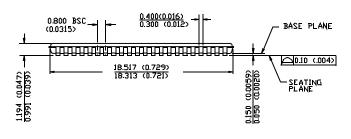
DIMENSION IN MM (INCH)

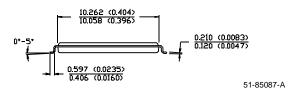
MAX

MIN.









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